Mathias Ekpu

List of Publications by Year
in descending order

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Version: 2024-02-01

9 papers	170 citations	1937685 4 h-index	1720034 7 g-index
9 all docs	9 docs citations	9 times ranked	141 citing authors

#	Article	IF	Citations
1	Finite element analysis of the effect of silver content for Snâ€“Agâ€“Cu alloy compositions on thermal cycling reliability of solder die attach. Engineering Failure Analysis, 2013, 28, 192-207.	4.0	54
2	Numerical study on thermal impacts of different void patterns on performance of chip-scale packaged power device. Microelectronics Reliability, 2012, 52, 1409-1419.	1.7	51
3	Fatigue life of lead-free solder thermal interface materials at varying bond line thickness in microelectronics. Microelectronics Reliability, 2014, 54, 239-244.	1.7	37
4	Investigation of effects of heat sinks on thermal performance of microelectronic package. , 2011, , .		16
5	The effect of thermal constriction on heat management in a microelectronic application. Microelectronics Journal, 2014, 45, 159-166.	2.0	5
6	Investigating the Reliability of SnAgCu Solder Alloys at Elevated Temperatures in Microelectronic Applications. Journal of Electronic Materials, 2021, 50, 4433-4441.	2.2	4
7	Reliability analysis of SnAgCu lead-free solder thermal interface materials in microelectronics. Soldering and Surface Mount Technology, 2021, ahead-of-print, .	1.5	2
8	Effect of Elevated Temperatures on SAC305 Solder Alloy Thermal Interface Material in a Microelectronic Assembly. FUOYE Journal of Engineering and Technology, 2021, 6, .	0.2	1
9	Effect of Tensile Load on the Mechanical Properties of AlSiC Composite Materials using ANSYS Design Modeller. Nigerian Journal of Technological Development, 2021, 17, 301-305.	0.6	0